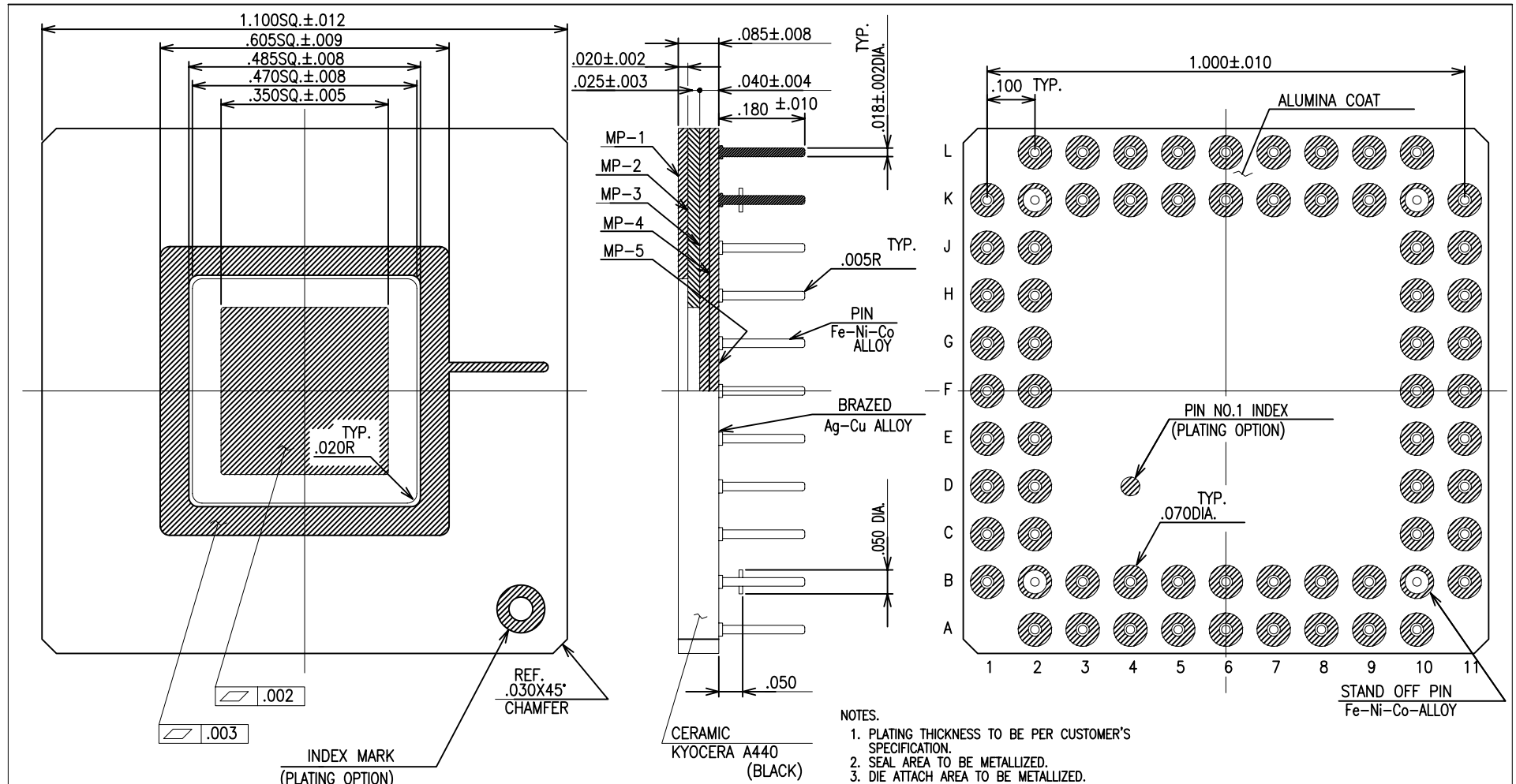


SSM P/N CPG06820



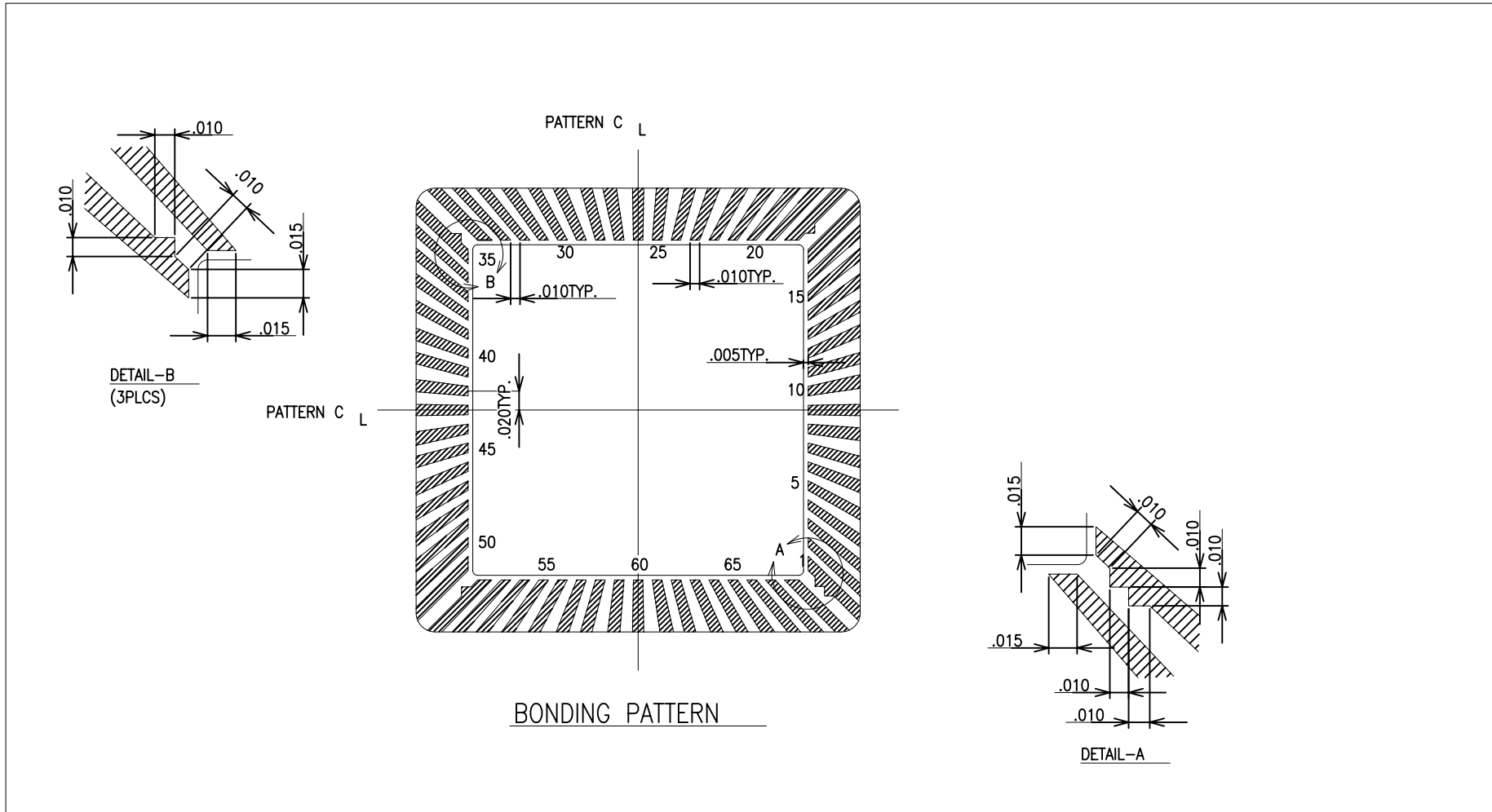
- NOTES.
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE: 0.5 ?MAX.

PB068P403-1 S=0 D=0

MODIFICATION						NAME 68 PIN GRID ARRAY PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005 THIRD ANGLE PROJECTION	DRAWN M.K	CHECKED M.S	APPROVED	DATE JUN.21 '84
	△	CONVERTED CAD DATA. CHANGED	DATE MAR.30 '98	E.K	H.S/S.NI	T.A	MATERIAL AS INDICATED	DRAWING NO. KD-84403-A		SHEET 1/3	



SSM P/N CPG06820



MODIFICATION						NAME 68 PIN GRID ARRAY PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN M.K	CHECKED M.S	APPROVED	DATE JUN.21.'94
						SCALE 10 / 1	MATERIAL				
	△	CONVERTED CAD DATA. CHANGED	MAR.30.'98	E.K	H.S/S.NI	T.A					
		DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION KYOTO JAPAN	THIRD ANGLE PROJECTION	DRAWING NO. KD-84403-A		SHEET 2 / 3	



WIRE BOND PAD / CONNECTOR

PIN INTERCONNECTION PLAN


W/B NO.	PIN NO.
1	B2
2	B1
3	C2
4	C1
5	D2
6	D1
7	E2
8	E1
9	F2
10	F1
11	G2
12	G1
13	H2
14	H1
15	J2
16	J1
17	K1
18	K2
19	L2
20	K3

W/B NO.	PIN NO.
21	L3
22	K4
23	L4
24	K5
25	L5
26	K6
27	L6
28	K7
29	L7
30	K8
31	L8
32	K9
33	L9
34	L10
35	K10
36	K11
37	J10
38	J11
39	H10
40	H11

W/B NO.	PIN NO.
41	G10
42	G11
43	F10
44	F11
45	E10
46	E11
47	D10
48	D11
49	C10
50	C11
51	B11
52	B10
53	A10
54	B9
55	A9
56	B8
57	A8
58	B7
59	A7
60	B6

W/B NO.	PIN NO.
61	A6
62	B5
63	A5
64	B4
65	A4
66	B3
67	A3
68	A2

S/R	NC
D/A	NC

MODIFICATION						NAME 68 PIN GRID ARRAY PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN M.K	CHECKED M.S	APPROVED	DATE JUN.21.'84
						SCALE X	MATERIAL				
	△	CONVERTED CAD DATA. CHANGED	MAR.30.'98	E.K	H.S/S.NI	T.A		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-84403-A		SHEET 3/3

